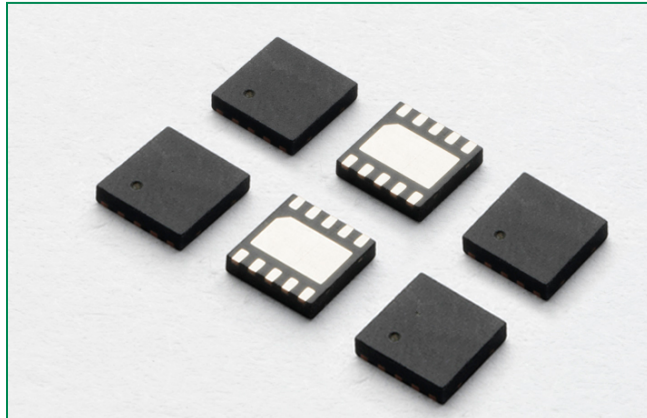
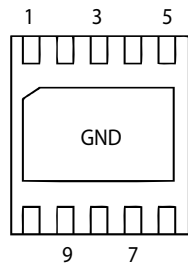


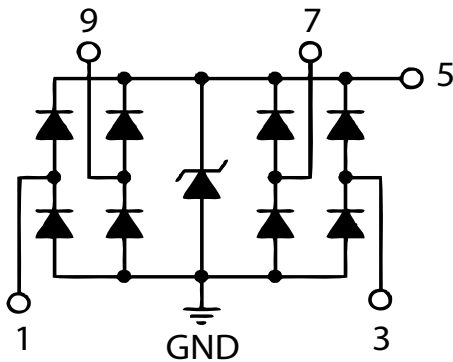
**SP3304N Series 3.3V 20A Diode Array**



**Pinout**



**Functional Block Diagram**



**Additional Information**



Datasheet



Resources



Samples

**Description**

The SP3304N integrates 4 channels of low capacitance diodes with an additional zener diode to protect sensitive I/O pins against lightning induced surge events and ESD. This robust device can safely absorb up to 20A per IEC 61000-4-5 2nd edition ( $t_p=8/20\mu s$ ) without performance degradation and a minimum  $\pm 30kV$  ESD per IEC 61000-4-2 international standard. The low loading capacitance makes the SP3304N ideal for protecting high-speed signal pins.

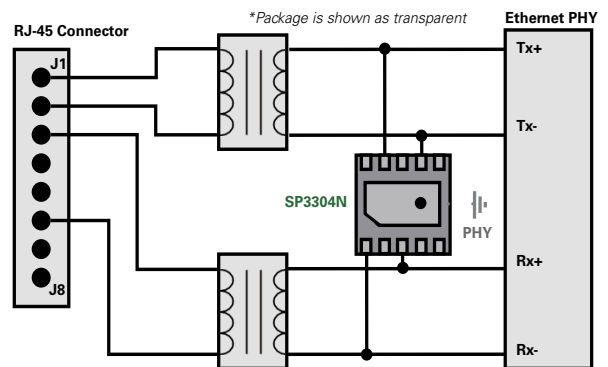
**Features**

- RoHS compliant, lead-free and halogen-free
- ESD, IEC 61000-4-2,  $\pm 30kV$  contact,  $\pm 30kV$  air
- EFT, IEC 61000-4-4, 40A ( $t_p=5/50ns$ )
- Lightning, IEC 61000-4-5 2nd edition, 20A ( $t_p=8/20\mu s$ )
- Low capacitance of 3.5pF (TYP) per I/O
- Low leakage current of 1 $\mu A$  (MAX) at 3.3V
- Moisture Sensitivity Level (MSL Level-1)

**Applications**

- 10/100/1000 Ethernet Interfaces
- Customer Premise Equipment (CPE)
- VoIP Phones
- Set Top Boxes
- PBX Systems
- Small Cells

**Application Example**



Life Support Note:

**Not Intended for Use in Life Support or Life Saving Applications**

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$I_{PP}$	Peak Current ( $t_p=8/20\mu s$ )	20.0	A
$P_{PK}$	Peak Pulse Power ( $t_p=8/20\mu s$ )	300	W
$T_{OP}$	Operating Temperature	-40 to 125	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### Thermal Information

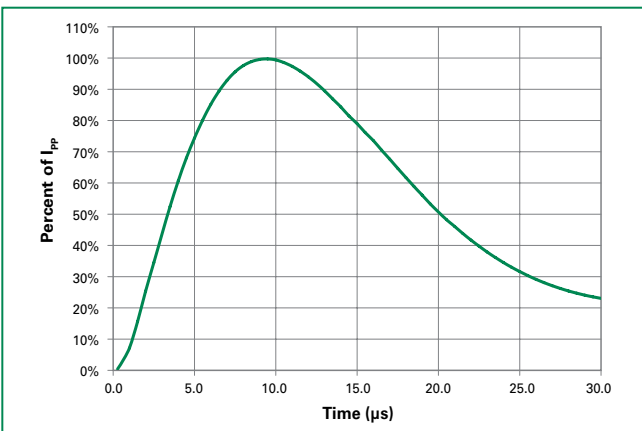
Parameter	Rating	Units
Storage Temperature Range	-55 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

### Electrical Characteristics ( $T_{OP}=25^\circ C$ )

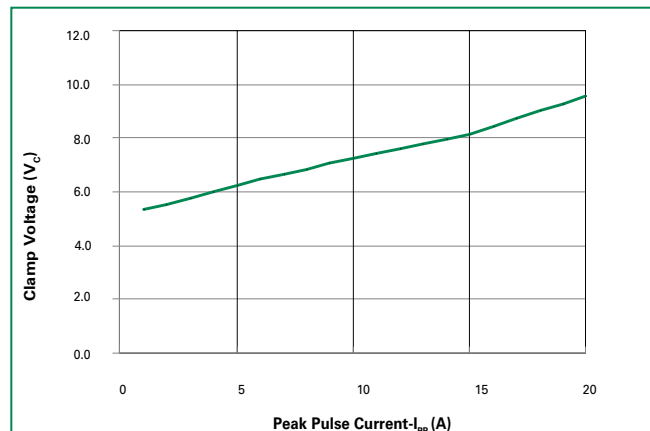
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	$V_{RWM}$				3.3	V
Punch Through Voltage	$V_{PT}$	$I_{PT}=5\mu A$	3.5			V
Snap Back Voltage	$V_{SB}$	$I_{SB}=50mA$	2.8			V
Reverse Leakage Current	$I_{LEAK}$	$V_R=2.5V$ , I/O to GND		0.5	1.0	$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A$ , $t_p=8/20\mu s$ , Fwd			6.0	V
		$I_{PP}=5A$ , $t_p=8/20\mu s$ , Fwd			7.0	V
		$I_{PP}=10A$ , $t_p=8/20\mu s$ , Fwd			8.0	V
		$I_{PP}=20A$ , $t_p=8/20\mu s$ , Fwd			11.5	V
Dynamic Resistance	$R_{DYN}$	$(V_{C2}-V_{C1})/(I_{PP2}-I_{PP1})$		0.25		$\Omega$
ESD Withstand Voltage <sup>1</sup>	$V_{ESD}$	IEC61000-4-2 (Contact)	$\pm 30$			kV
		IEC61000-4-2 (Air)	$\pm 30$			kV
Diode Capacitance <sup>1</sup>	$C_{I/O-GND}$	Reverse Bias=0V		3.5	5.0	pF
Diode Capacitance <sup>1</sup>	$C_{I/O-I/O}$	Reverse Bias=0V		2.0		pF

Note: <sup>1</sup> Parameter is guaranteed by design and/or device characterization.

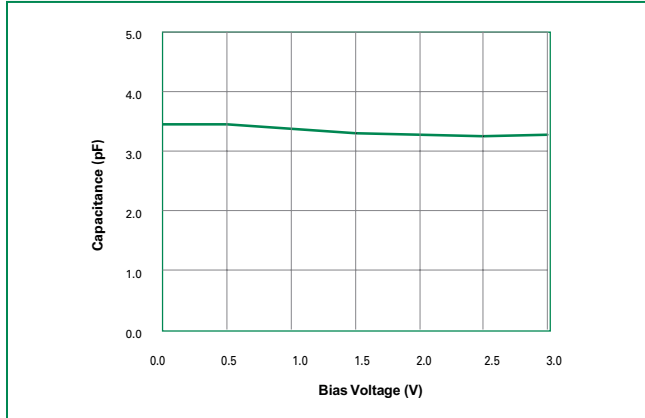
### Pulse Waveform



### Clamping Voltage vs. $I_{PP}$



**Capacitance vs. Bias**

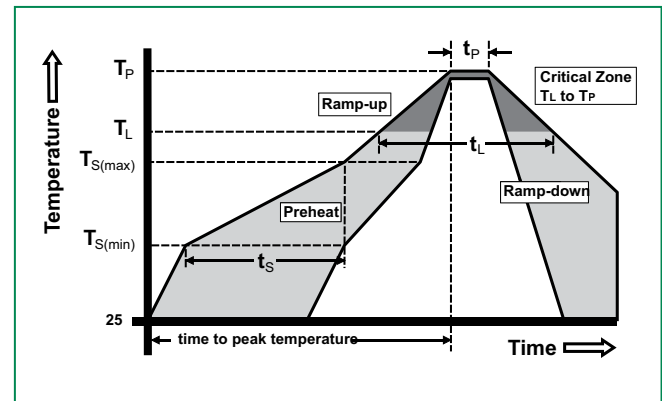


**Ordering Information**

Part Number	Package	Marking	Min. Order Qty.
SP3304NUTG	μDFN-10	UH4	3000

**Soldering Parameters**

Reflow Condition	Pb – Free assembly	
Pre Heat	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus) Temp ( $T_L$ ) to peak		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260 <sup>+0/-5</sup> °C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes Max.
Do not exceed		260°C



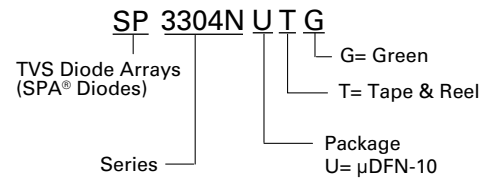
**Product Characteristics**

Lead Plating	Pre-Plated Frame
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substitute Material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

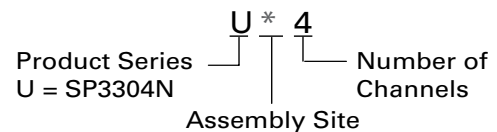
Notes :

1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.

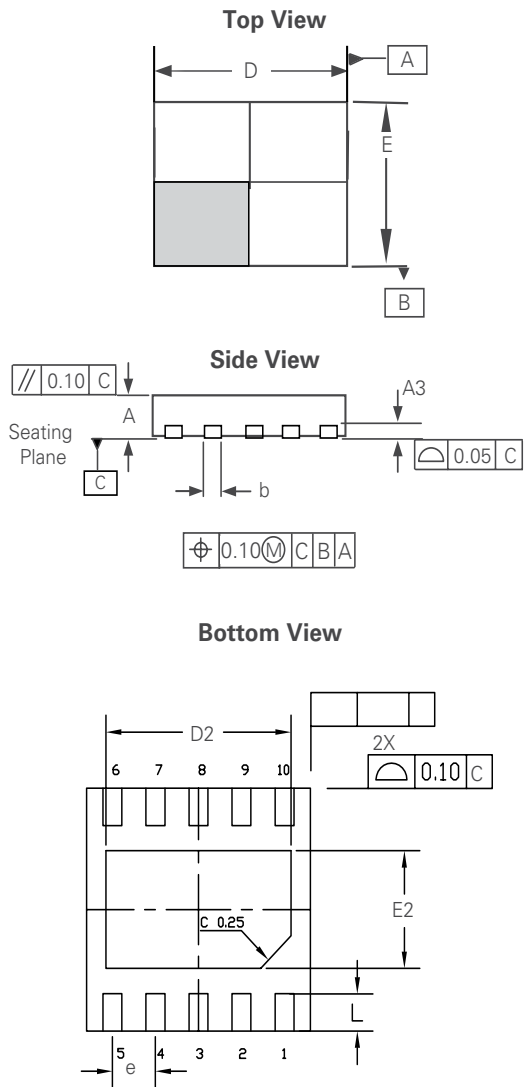
**Part Numbering System**



**Part Marking System**

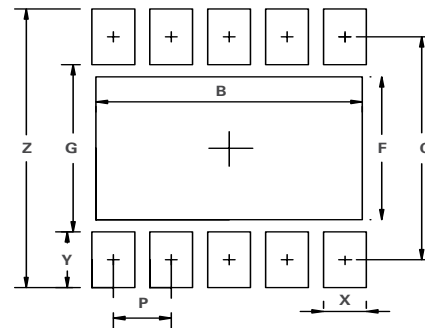


**Package Dimensions —  $\mu$ DFN-10**



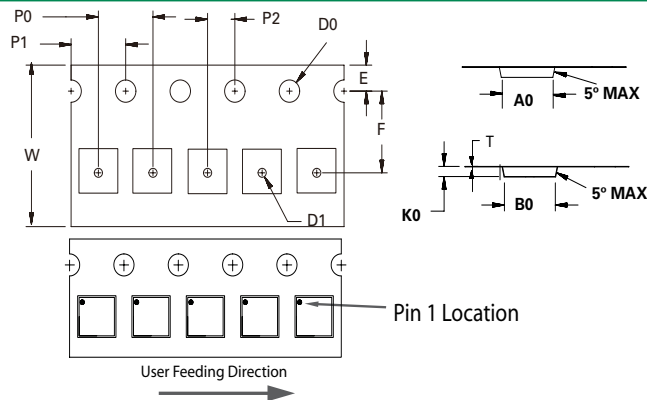
Package	$\mu$ DFN-10 (2.6x2.6mm)					
JEDEC	MO-229					
Symbol	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.45	0.50	0.55	0.018	0.020	0.022
A3	0.130 Ref			0.005 Ref		
b	0.17	0.22	0.27	0.006	0.008	0.010
D	2.50	2.60	2.70	0.097	0.101	0.105
D2	2.10	2.15	2.20	0.081	0.083	0.085
E	2.50	2.60	2.70	0.097	0.101	0.105
E2	1.21	1.26	1.31	0.046	0.049	0.051
e	0.50 BSC			0.020 BSC		
L	0.35	0.40	0.45	0.014	0.016	0.018

Recommended Solder Pads  $\mu$ DFN-10L 2.6x2.6mm



Dimension		
Symbol	Millimeters	Inches
B	2.30	0.091
C	2.20	0.087
F	1.41	0.056
G	1.65	0.065
P	0.50	0.020
X	0.37	0.015
Y	0.55	0.022
Z	2.75	0.108

**Embossed Carrier Tape & Reel Specification —  $\mu$ DFN-10 (2.6x2.6mm)**



Symbol	Millimeters
A0	2.82 ± 0.05
B0	2.82 ± 0.05
D0	∅1.50 + 0.10
D1	∅0.50 + 0.05
E	1.75 ± 0.10
F	3.50 ± 0.05
K0	0.76 ± 0.05
P0	4.00 ± 0.10
P1	4.00 ± 0.10
P2	2.00 ± 0.05
T	0.25 ± 0.02
W	8.00 + 0.30 / - 0.10

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